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(54) SEMICONDUCTOR DEVICE FOR CHIP-ON-CHIP

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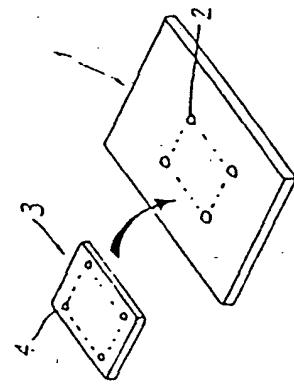
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PURPOSE: To easily realize an all-in-one device and to simplify a process by applying the other chip including an E²PROM element on one chip including a semiconductor element necessary for a wafer process different from the E² PROM element by a face-down bonding.

CONSTITUTION: In order to manufacture an all-in-one device in which all functions are unified on the same wafer by an all-in-one process, an E²PROM element necessary for a different wafer process and other elements adhere by a protruding electrode 2 formed on chips including the element on a base chip 1 with the chip including the latter element as a base by a chip-on-chip by face-down bonding. Thus, satisfactory products can be selected as chips, and since the chip may be placed on the chip, a process is simplified, and the chip size can be reduced.



LEGENDE zu den Bibliographiedaten

(54) Titel der Patentanmeldung

(11) Nummer der JP-A2 Vordr/entlichung

(21) Aktenzettel der JP-Anmeldung

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